

## Packaging Japan TC Chapter Meeting Summary and Minutes

SEMI Japan Standards Spring 2014 Meetings  
Thursday, May 8, 2014, 15:00-17:00  
SEMI Japan, Tokyo, Japan

### Next Committee Meeting

SEMI Japan Standards Summer 2014 Meetings  
Monday, July 14, 2014, 15:15-17:00  
SEMI Japan, Tokyo, Japan

### Table 1 Meeting Attendees

**Co-Chairs:** Kazunori Kato (AiT), Masahiro Tsuriya (iNEMI)

**SEMI Staff:** Naoko Tejima (SEMI Japan)

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
Tokyo Seimitsu	Chiba	Kiyotaka	Toray Engineering	Nishimura	Koji
Toray Engineering	Funahashi	Takanori	Shin-Etsu Polymer	Ohde	Shoko
AiT	Kato	Kazunori	AIST	Shimamoto	Haruo
The University of Tokyo	Kawai	Naoyuki	Micron Memory Japan	Sonobe	Kaoru
AET	Kiyono	Mikio	Asahi Glass	Takahashi	Mamoru
Shin-Etsu Polymer	Maekawa	Mitsunori	Harima Chemicals Group	Terada	Nobuto
Disco	Masuchi	Sumio	iNEMI	Tsuriya	Masahiro
Hitachi Kokusai Electric	Matsuda	Mitsuhiro	Hitachi High-Technologies	Yoshino	Eiji
Consultant	Nakamura	Kazuhiko	SEMI Japan	Tejima	Naoko

\* alphabetical order by last name

### Table 2 Leadership Changes

None.

### Table 3 Ballot Results

**Passed** ballots and line items will be forwarded to the ISC Audit & Review Subcommittee for procedural review.

**Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting.

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
5691	Doc.#5691, New Standard: Test Method for Measurement of Chip (Die) Strength by Mean of Cantilever Bending	<b>Passed</b> as ballotted

### Table 4 Authorized Ballots

None.

## Table 5 Authorized Activities

None.

**Table 6 New Action Items (or move to Section 8, Action Item Review)**

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
PKG140508-1	SEMI Staff	To forward adjudication result of Doc.#5691 to the ISC A&R Subcommittee for procedural review.
PKG140508-2	Masahiro Tsuruya	To draft the PKG Committee Charter, modifying the description of EHS and 3D-IC.
PKG140508-3	Masahiro Tsuruya	To draft the consensus opinion of JA PKG Committee to the organization corresponding to the NA 3DS-IC Committee.
PKG140508-4	Thin Chip Handling TF	To prepare SNARF and submit it at the next JA TC Chapter Meeting.

## 1 Welcome, Reminders and Introductions

Masahiro Tsuruya, committee co-chair, called the meeting to order at 15:00. Self-introductions were made followed by the agenda review.

## 2 Required Meeting Elements

The meeting reminders on program membership requirement, antitrust issues, intellectual property issues and international effective meeting guidelines, were reviewed by SEMI staff, Naoko Tejima.

## 3 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting held on March 20, 2014.

**Motion:** To approve the minutes of the previous meeting as written.

**By / 2<sup>nd</sup>:** Kazuhiko Nakamura (Consultant) / Kaoru Sonobe (Micron Memory Japan)

**Discussion:** None

**Vote:** 10 in favor and 0 opposed. **Motion passed.**

**Attachment:** 01\_JA\_PKG\_Previous\_Mtg\_Minutes\_140508

## 4 SEMI Staff Report

Naoko Tejima gave the SEMI staff report. This report included SEMI Global 2014 Calendar of Events, Global Standards Meeting Schedule, NA Standards at SEMICON West 2014 Meetings, 2014 Critical Dates for SEMI Standards Ballots, SEMI Standards Publication, A&R Ballot Review and Contact Information.

**Attachment:** 02\_SEMI\_Staff\_Report\_140508

## 5 Liaison Reports

### 5.1 Japan Regional Standards Committee (JRSC)

Kazunori Kato reported for the Japan Regional Standards Committee (JRSC). Of note:

- PV Automation Japan TC Chapter requests JRSC to support and propose Transformation of the Global PV Automation Committee to the Global Factory Automation Technology Committee to ISC, and it was approved.
- JRSC Planning meeting in this summer will be passed up, if the suitable theme will not be found.
- The guideline of the TF meeting operation was proposed by SEMI and the detail will be reported at the next TC Chapter meeting.

### 5.2 North America 3DS-IC Committee Report

Naoko Tejima briefly reported for the North America 3DS-IC Committee. This report included Leadership, Organization Chart, Meeting Information, Document Review Summary, SNARFs, Issued NA 3DS-IC Ballots, Other Current Activities, NA 3DS-IC SEMICON West 2014 Meeting Schedule and Contact information.

**Attachment:** 03\_NA\_3DS-IC\_Comm\_Report\_140508

### 5.3 Taiwan 3DS-IC Committee Report

Naoko Tejima briefly reported for the Taiwan 3DS-IC Committee. This report included Leadership, Organization Chart, Meeting Information, SNARFs, Published Standards and Contact Information.

**Attachment:** 04\_TW\_3DS-IC\_Comm\_Report\_140508

## 6 Ballot Review

### 6.1 Doc.#5691, New Standard: Test Method for Measurement of Chip (Die) Strength by Mean of Cantilever Bending.

This document passed committee review and will be forwarded to the ISC A&R SC for procedural review.

**Action Item:** SEMI staff to forward adjudication result of Doc.#5691 to the ISC A&R Subcommittee for procedural review.

**Attachment:** 05\_Ballot\_Report\_for\_5691\_140508

## 7 Task Force Reports

### 7.1 Electromagnetic Characterization Study Group

Mikio Kiyono reported for the Electromagnetic Characterization Study Group. Of note:

- SG is going on discussion with JEITA LPB (LSI Package and Board) Working Group.
- SG is planning to held Tutorial Seminar or Symposium to go ahead with this standard.

**Attachment:** 06\_ElectromagneticCharacterization\_SG\_Report\_140508

### 7.2 DFM Study Group

No report was provided by the Task Force.

### 7.3 450mm Japan Assembly & Test Die Preparation Task Force

Sumio Masuchi reported for 450mm Japan Assembly & Test Die Preparation Task Force. There were no particular progress should be reported since the previous committee meeting.

**Attachment:** 07\_450mm\_JA\_ATDP\_TF\_Report\_140508

### 7.4 Fiducial Mark Interoperability Task Force

Sumio Masuchi reported for the Fiducial Mark Interoperability Task Force. There were no particular progress should be reported since the previous committee meeting.

**Attachment:** 08\_Fiducial\_Mark\_Interoperability\_TF\_Report\_140508

### 7.5 Thin Die Bending Strength Measurement Method Task Force

Haruo Shimamoto reported on progress for the Thin Chip Die Bending Strength Measurement Method Task Force. Of note:

- Doc.#5691, New Standard: Test Method for Measurement of Chip (Die) Strength by Mean of Cantilever Bending, passed committee review as previously discussed. (See 6.1)
- TF is planning to submit the technical paper to JIEP Proceedings Vol. Sept-2014.
- TF is also planning to add the Flow Chart as “Related Information” or “Appendix”.

**Attachment:** 09\_Thin\_Die\_Bending\_Strength\_Measurement\_Method\_TF\_Report\_140508

### 7.6 Thin Chip Handling Task Force

Kazuhiko Nakamura reported on progress for the Thin Chip Handling Task Force. Of note:

- The kick off meeting was held April 11.
- TF is working for the contents of SNARF. The 1<sup>st</sup> draft will be developed by July, and the technical ballot will be submitted in October

**Action Item:** Thin Chip Handling TF to prepare SNARF and submit it at the next JA TC Chapter Meeting.

**Attachment:** 10\_Thin\_Chip\_Handling\_TF\_Report\_140508

### 7.7 5-Year-Review Task Force

Masahiro Tsuruya reported for the 5-Year-Review Task Force. The kick off meeting was held earlier in the day. Of note:

- 32 documents are for 5-year-review procedure in 2014.

**Attachment:** 11\_5-Yrs\_Review\_TF\_Update\_140508

### 7.8 3D-IC Study Group

Masahiro Tsuruya reported on progress for the 3D-IC Study Group. Of note:

- Shared the survey results which was made from April 16 - May 2, and on the basis of them, the future activities of SG were discussed.

**Attachment:** 12\_3D-IC\_SG\_Report\_140508

## 8 Old Business

### 8.1 Previous Meeting Action Items

Naoko Tejima reviewed the previous meeting action items.

**Table 7 Previous Meeting Actions Items**

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
PKG130719-9	Co-chairs	To review all SNARFs and check whether they are written in the right way. <b>Close</b>
PKG140320-1	SEMI staff	To forward adjudication result of Doc.#5636 to the ISC A&R Subcommittee for procedural review. <b>Close</b>
PKG140320-2	SEMI staff	To report about the MEMS Activities regarding to Packaging at the committee meeting, if any. <b>Close</b>
PKG140320-3	SEMI staff	To forward the teleconference information of 3DS-IC Committee at NA Standards Spring 2014 Meetings. <b>Close</b>
PKG140320-4	SEMI staff	To submit the new committee charter to JRSC to get their approval. <b>Close</b>
PKG140320-5	SEMI staff	To attach the document list of 5year review procedure to the meeting minutes. <b>Close</b>

## 9 New Business

### 9.1 Review of the Committee Charter of Packaging Committee

Mitsuhiro Matsuda, Co-chairs of JRSC, pointed out the following to the draft of the Packaging Committee Charter prior to propose JRSC.

- Description about EHS: If there are not activities regarding to EHS actually, this description should be deleted, since it is likely to cause misunderstanding.
  - The description means Environmentally-conscious Product. It will be modified.
- Description of 3D-IC is included to the charter.
  - The description of 3D-IC here is in the broad sense of the term..
- The above 2 points seems to be within the editorial changes, and it is only necessary to get approval of JRSC.

**Action Item:** Masahiro Tsuruya to draft the PKG Committee Charter, modifying the description of EHS and 3D-IC.

**Action Item:** Masahiro Tsuruya to draft the consensus opinion of JA PKG Committee to the organization corresponding to the NA 3DS-IC Committee.

**Attachment:** 13\_PKG\_Committee\_Charter\_140508

## 10 Action Item Review

### 10.1 New Action Items

Naoko Tejima reviewed the new action items. These can be found in the New Action Items table at the beginning of these minutes.

## 11 Next Meeting and Adjournment

The next meeting of the Japan Packaging Committee is scheduled for Monday, July 14, 2014, 15:15-17:00, at SEMI Japan, Tokyo, Japan.

Respectfully submitted by:  
Naoko Tejima  
Manager, Standards  
SEMI Japan  
Phone: +81.3.3222.5804  
Email: ntejima@semi.org

Minutes approved by:

Kazunori Kato (AiT), Co-chair	June 17, 2014
Masahiro Tsuruya (iNEMI), Co-chair	June 17, 2014

**Table 8 Index of Available Attachments #1**

#	<i>Title</i>
1	JA_PKG_Previous_Mtg_Minutes_140508
2	SEMI_Staff_Report_140508
3	NA_3DS-IC_Comm_Report_140508
4	TW_3DS-IC_Comm_Report_140508
5	Ballot_Report_for_5691_140508
6	Packages_and_Packaging_Materials_Eco-efficiency_TF_Report_140508
7	450mm_JA_ATDP_TF_Report_140508
8	Fiducial_Mark_Interoperability_TF_Report_140508
9	Thin_Die_Bending_Strength_Measurement_Method_TF_Report_140508
10	Thin_Chip_Handling_TF_Report_140508
11	5-Yrs_Review_TF_Update_140508
12	3D-IC_SG_Report_140508
13	PKG_Committee_Charter_140508_140508

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at [www.semi.org](http://www.semi.org). For additional information or to obtain individual attachments, please contact Naoko Tejima at the contact information above.